
Hardware Design Checklist

1.0 INTRODUCTION

This document provides a hardware design checklist for the Microchip KSZ8061MNX. These checklist items should be followed when utilizing the KSZ8061MNX in a new design. A summary of these items is provided in [Section 9.0, "Hardware Checklist Summary," on page 9](#). Detailed information on these subjects can be found in the corresponding section:

- [Section 2.0, "General Considerations"](#)
- [Section 3.0, "Power"](#)
- [Section 4.0, "Ethernet Signals"](#)
- [Section 5.0, "Clock Circuit"](#)
- [Section 6.0, "Digital Interfaces"](#)
- [Section 7.0, "Startup"](#)
- [Section 8.0, "Miscellaneous"](#)

2.0 GENERAL CONSIDERATIONS

2.1 Pin Check

Check the pinout of the part against the data sheet. Ensure that all pins match the data sheet and are configured as inputs, outputs, or bidirectional for error checking.

2.2 Ground

- The ground pins, **GND**, should be connected to the solid ground plane on the board.
- It is recommended that all ground connections be tied together to the same ground plane. Separate ground planes are not recommended.

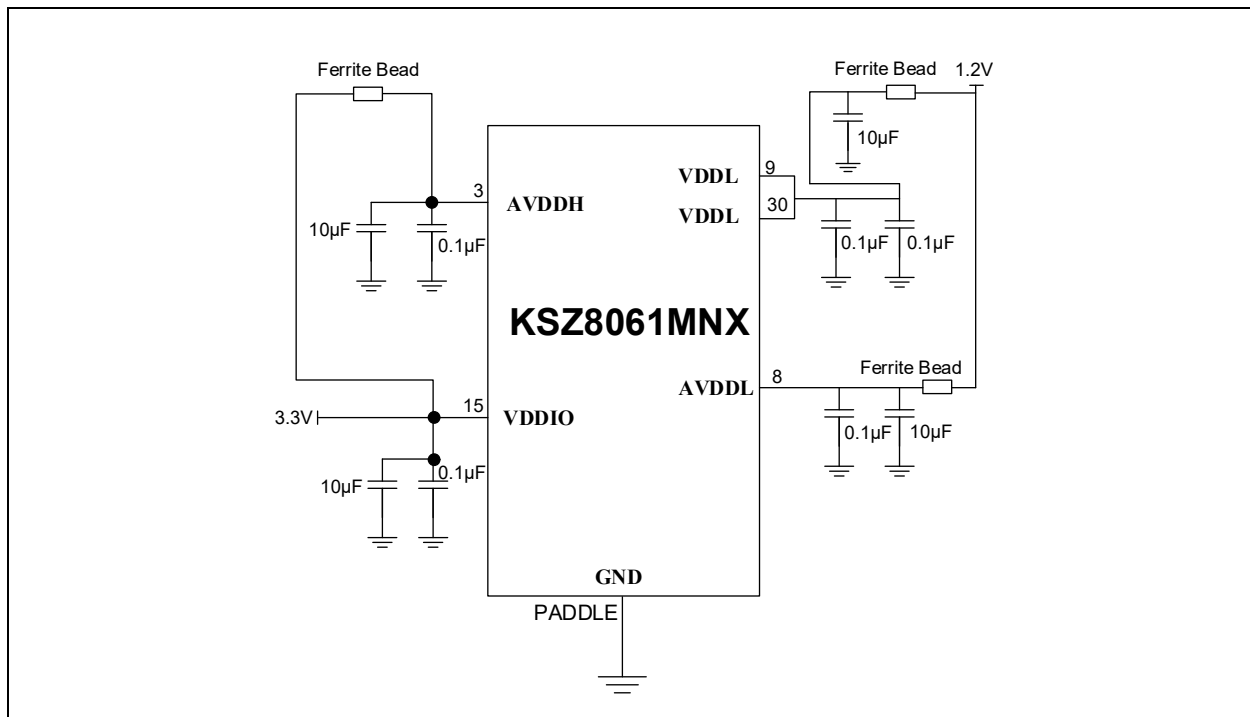
KSZ8061MNX

3.0 POWER

- The analog supply (AVDDH) is located on pin 3, and requires a connection from +3.3V through a ferrite bead. Bulk capacitance should be placed on each side of the ferrite bead. Generally, a 100-220 Ω (at 100 MHz) ferrite bead is used.
- The AVDDH pin should include 0.1 μ F and 10 μ F capacitors to decouple the device. The capacitor size should be SMD_0603 or smaller.
- Pin 15 (VDDIO) is the variable supply voltage for the I/O pads. This pin should be connected to the +3.3V, 2.5V, or 1.8V supply. A bulk capacitor is needed close to the source to prevent any droop in the supply when the part starts. Decoupling capacitors need to be placed as close to the part as possible to reduce high frequency noise being injected through EMI interference.
- Pin 8 (AVDDL) supplies power to the KSZ8061MNX analog core. Decouple with 10 μ F and 0.1 μ F capacitors to ground and join them to the power trace or plane.
- Pins 9 and 30 (VDDL) supply power to the KSZ8061MNX core. Decouple with 10 μ F and 0.1 μ F capacitors to ground and join them to the power trace or plane.

The power and ground connections are shown in [Figure 3-1](#).

FIGURE 3-1: POWER AND GROUND CONNECTIONS



Caution: This +1.2V supply is for internal logic only. Do *not* power other circuits or devices with this supply.

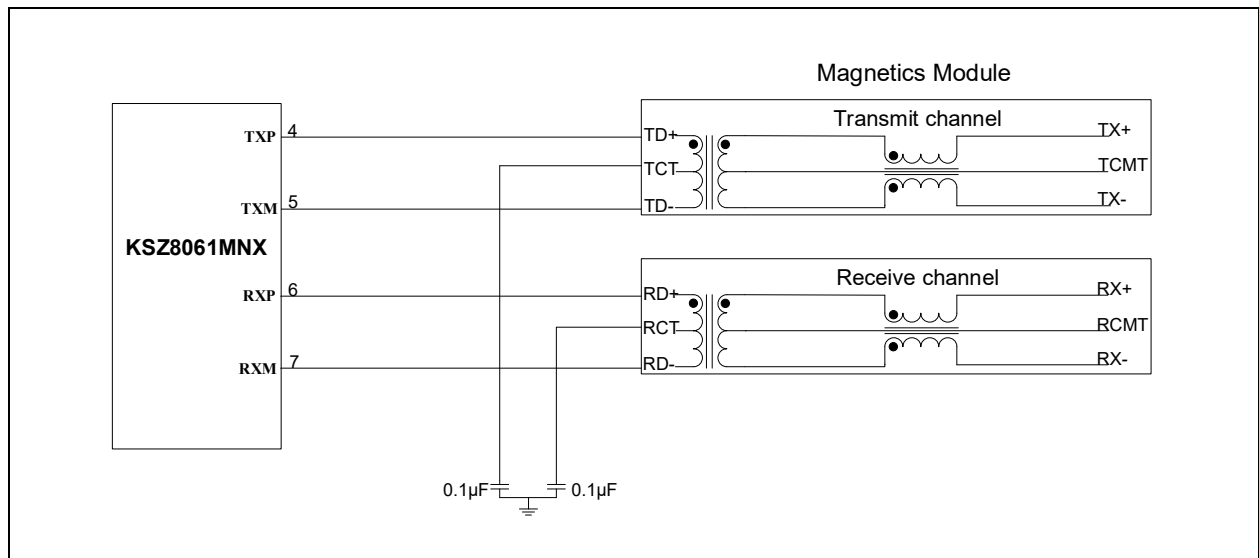
4.0 ETHERNET SIGNALS

4.1 PHY Interface

- **TXP** (pin 4): This pin is the transmit twisted pair output positive connection from the internal PHY. It has an internal terminator and a bias, so it can be directly connected to the transmit channel of the magnetics and no external terminator and bias are needed.
- **TXM** (pin 5): This pin is the transmit twisted pair output negative connection from the internal PHY. It has an internal terminator and a bias, so it can be directly connected to the transmit channel of the magnetics and no external terminator and bias are needed.
- **RXP** (pin 6): This pin is the receive twisted pair input positive connection to the internal PHY. It has an internal terminator and a bias, so it can be directly connected to the receive channel of the magnetics and no external terminator and bias are needed.
- **RXM** (pin 7): This pin is the receive twisted pair input negative connection to the internal PHY. It has an internal terminator and a bias, so it can be directly connected to the receive channel of the magnetics and no external terminator and bias are needed.

For transmit and receive channel connections details, refer to [Figure 4-1](#).

FIGURE 4-1: TRANSMIT AND RECEIVE CHANNEL CONNECTIONS



4.2 Magnetics Connection

- The center tap connection on the KSZ8061MNX side for the transmit channel only connects a 0.1 μF capacitor to GND and no bias is needed.
- The center tap connection on the KSZ8061MNX side for the receive channel only connects a 0.1 μF capacitor to GND and no bias is needed.
- The center taps of the magnetics of the transmit and receive channels should not be connected together.
- The center tap connection on the cable side (RJ45 side) for the transmit channel should be terminated with a 75Ω resistor through a 1000 pF, 2 kV capacitor to chassis ground.
- The center tap connection on the cable side (RJ45 side) for the receive channel should be terminated with a 75Ω resistor through a 1000 pF, 2 kV capacitor to chassis ground.
- Only one 1000 pF, 2 kV capacitor to chassis ground is required. It is shared by both TX and RX center taps.
- MDI Connections:
 - Pin 1 of the RJ45 is TX+ and should trace through the magnetics to TXP (pin 4) of the KSZ8061MNX.
 - Pin 2 of the RJ45 is TX- and should trace through the magnetics to TXM (pin 5) of the KSZ8061MNX.
 - Pin 3 of the RJ45 is RX+ and should trace through the magnetics to RXP (pin 6) of the KSZ8061MNX.
 - Pin 6 of the RJ45 is RX- and should trace through the magnetics to RXM (pin 7) of the KSZ8061MNX.

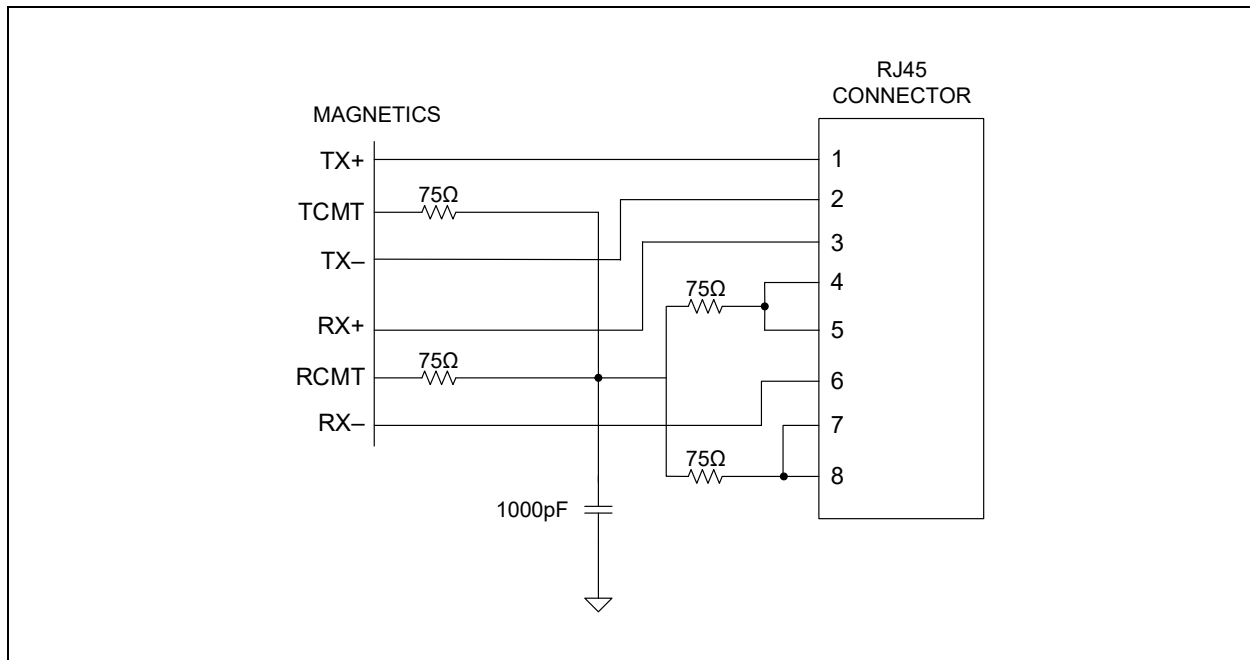
KSZ8061MNX

- MDIX Connections:
 - Pin 3 of the RJ45 is TX+ and should trace through the magnetics to TXP (pin 4) of the KSZ8061MNX.
 - Pin 6 of the RJ45 is TX- and should trace through the magnetics to TXM (pin 5) of the KSZ8061MNX.
 - Pin 1 of the RJ45 is RX+ and should trace through the magnetics to RXP (pin 6) of the KSZ8061MNX.
 - Pin 2 of the RJ45 is RX- and should trace through the magnetics to RXM (pin 7) of the KSZ8061MNX.
- When using the KSZ8061MNX device in the Auto MDIX mode of operation, the use of an Auto MDIX style magnetics module (that is, the one where the TX and RX channels are identical) is required.

4.3 RJ45 Connection

- Pins 4 and 5 of the RJ45 connector interface to one pair of unused wires in CAT-5 type cables. These should be terminated to chassis ground through a 1000 pF, 2 kV capacitor. There are two methods of accomplishing this:
 - Pins 4 and 5 can be connected together with two 49.9 Ω resistors. The common connection of these resistors should be connected through a third 49.9 Ω resistor to the 1000 pF, 2 kV capacitor.
 - For a lower component count, the resistors can be combined. The two 49.9 Ω resistors in parallel perform like a 25 Ω resistor. The 25 Ω resistor in series with the 49.9 Ω resistor causes the entire circuit to function as a 75 Ω resistor. So, by shorting pins 4 and 5 together on the RJ45 and terminating them with a 75 Ω resistor in series with the 1000 pF, 2 kV capacitor to chassis ground, an equivalent circuit is created.
- Pins 7 and 8 of the RJ45 connector interface to one pair of unused wires in CAT-5 type cables. These should be terminated to chassis ground through a 1000 pF, 2 kV capacitor. There are two methods of accomplishing this:
 - Pins 7 and 8 can be connected together with two 49.9 Ω resistors. The common connection of these resistors should be connected through a third 49.9 Ω resistor to the 1000 pF, 2 kV capacitor.
 - For a lower component count, the resistors can be combined. The two 49.9 Ω resistors in parallel perform like a 25 Ω resistor. The 25 Ω resistor in series with the 49.9 Ω resistor causes the entire circuit to function as a 75 Ω resistor. So, by shorting pins 7 and 8 together on the RJ45 and terminating them with a 75 Ω resistor in series with the 1000 pF, 2 kV capacitor to chassis ground, an equivalent circuit is created.
- The RJ45 shield should be attached directly to chassis ground.

FIGURE 4-2: RJ45 CONNECTIONS



5.0 CLOCK CIRCUIT

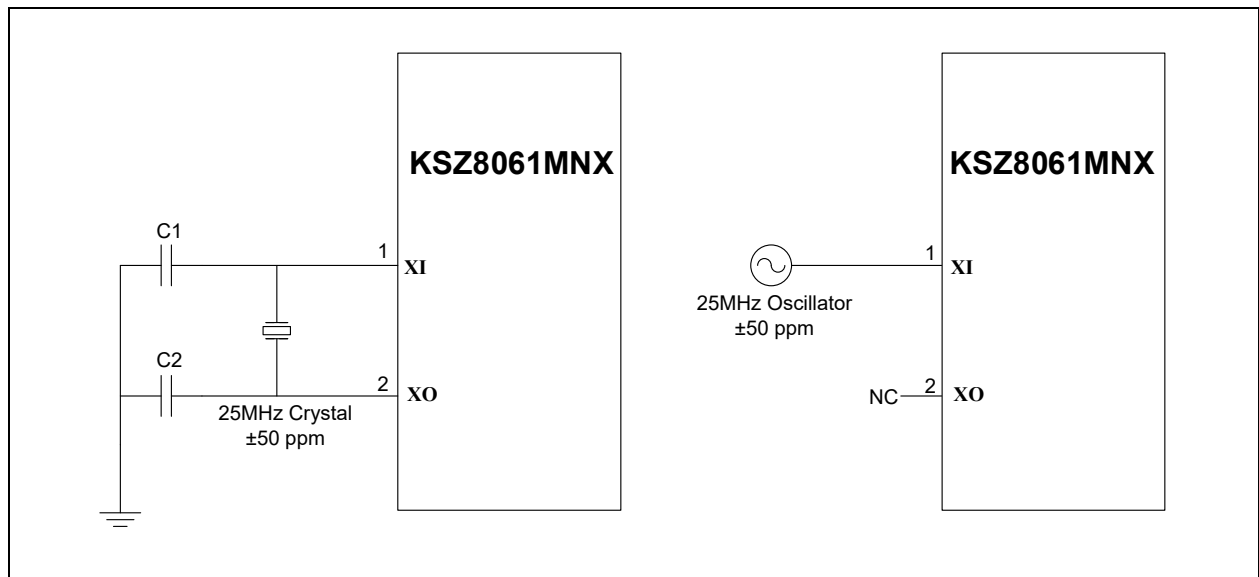
5.1 Crystal and External Oscillator/ Clock Connections for MII Mode

A 25.000 MHz (± 50 ppm) crystal should be used to provide the clock source. For exact specifications and tolerances, refer to the latest revision of the *KSZ8061MNX Data Sheet*.

- **XI** (pin 1) is the clock circuit input for the KSZ8061MNX device. This pin requires a capacitor to ground. One side of the crystal connects to this pin.
- **XO** (pin 2) is the clock circuit output for the KSZ8061MNX device. This pin requires a capacitor to ground. One side of the crystal connects to this pin.

Since every system design is unique, the capacitor values are system-dependent, based on the C_L spec of the crystal and the stray capacitance value. The PCB design, crystal, and layout all contribute to the characteristics of this circuit. Alternatively, a 25.000 MHz, 3.3V clock oscillator may be used to provide the clock source for the KSZ8061MNX. When using a single-ended clock source, **XO** (pin 2) should be left floating as a No Connect (NC).

FIGURE 5-1: CRYSTAL AND OSCILLATOR CONNECTIONS



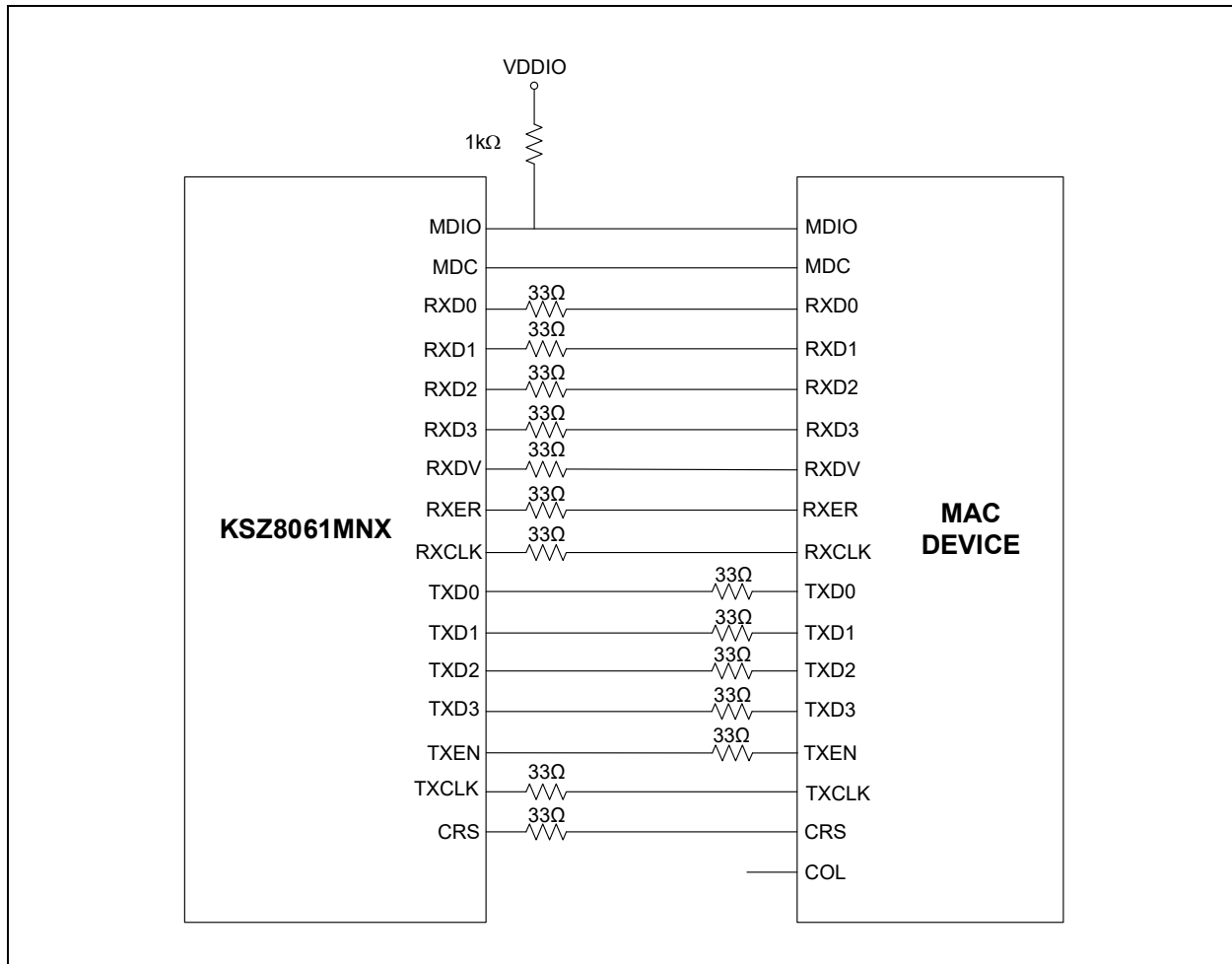
KSZ8061MNX

6.0 DIGITAL INTERFACES

6.1 MII Interface

- When utilizing either an external MII MAC interface or an MII connector, the following table indicates the proper connections for the 16 signals, including two management pins (MDC and MDIO).
- Provisions should be made for series terminations for all outputs on the MII interface. Series resistors enable the designer to closely match the output driver impedance of the KSZ8061MNX and the PCB trace impedance to minimize ringing on the signals. Exact resistor values are application-dependent and must be analyzed in-system. A suggested starting point for the value of these series resistors is 33Ω.

FIGURE 6-1: KSZ8061MNX MII CONNECTIONS



6.2 Required External Pull-ups

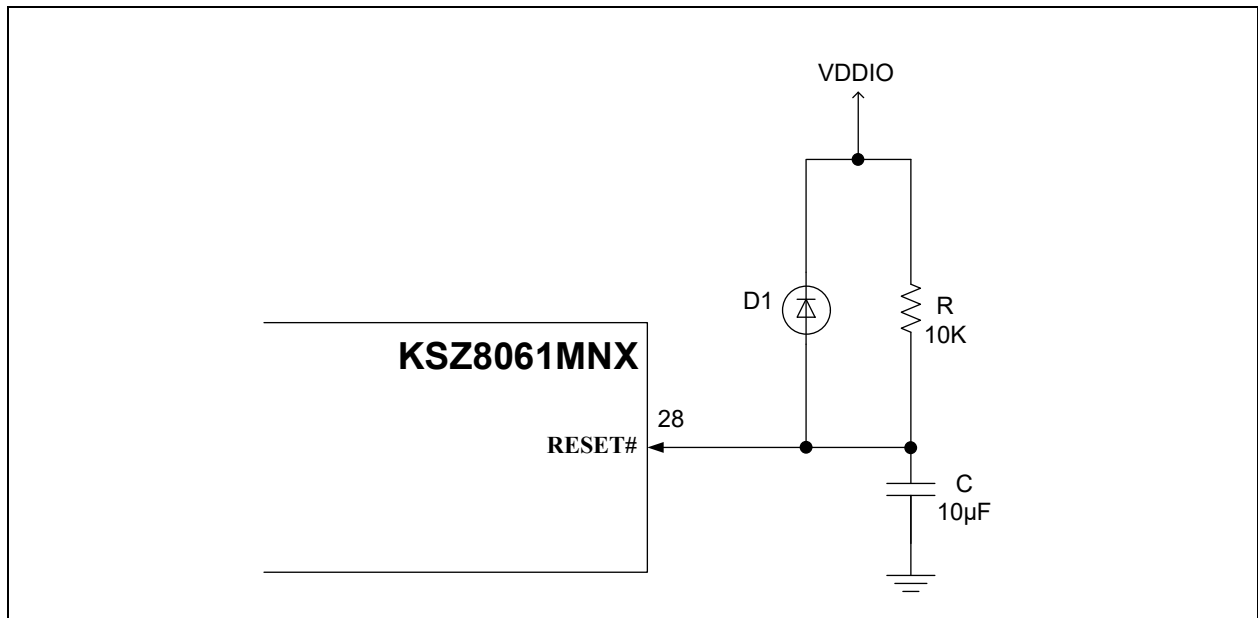
- When using the KSZ8061MNX MDC/MDIO management pins, a pull-up resistor of 1 kΩ on the MDIO signal (pin 16) is required.
- If used, the **INTRP** pin (pin 29) requires a 4.7 kΩ external pull-up resistor since this output is an open drain. If the **INTRP** pin is not used, then this pin can float.

7.0 STARTUP

7.1 Reset Circuit

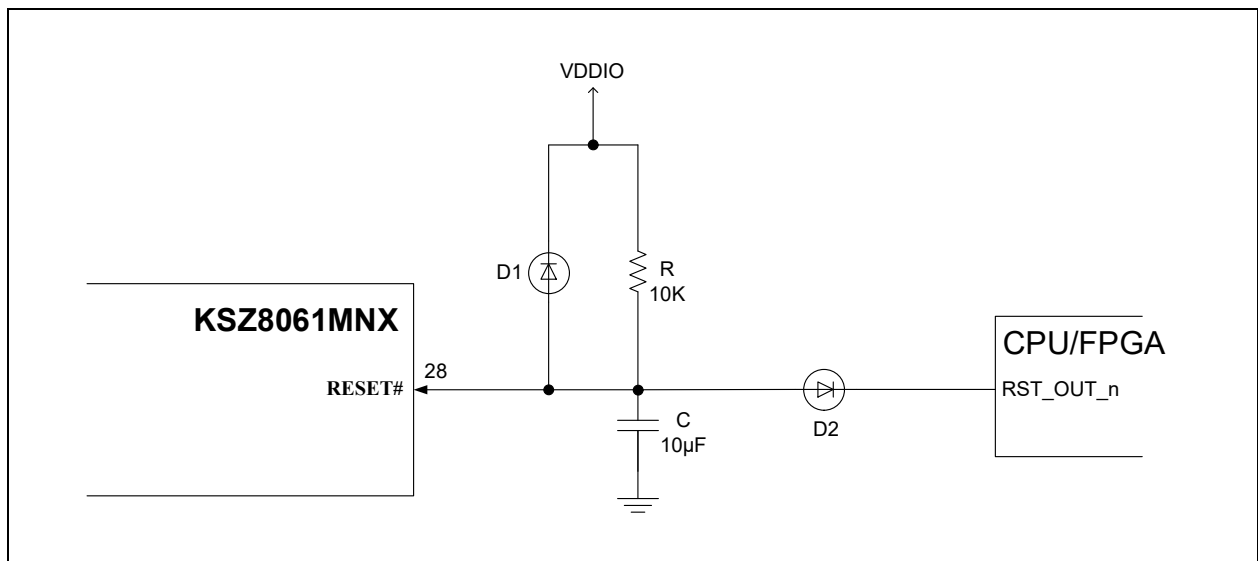
RESET# (pin 28) is an active-low reset input. This signal resets all logic and registers within the KSZ8061MNX. A hardware reset (**RESET#** assertion) is required following power-up. Refer to the latest copy of the *KSZ8061MNX Data Sheet* for reset timing requirements. [Figure 7-1](#) shows a recommended reset circuit for powering up the KSZ8061MNX when reset is triggered by the power supply.

FIGURE 7-1: RESET TRIGGERED BY POWER SUPPLY



[Figure 7-2](#) details the recommended reset circuit for applications where reset is driven by an external CPU or FPGA. The reset out pin (**RST_OUT_n**) from the CPU/FPGA provides the warm reset after power-up. If the Ethernet device and CPU/FPGA use the same VDDIO voltage, D2 can be removed and both reset pins can be directly connected.

FIGURE 7-2: RESET CIRCUIT INTERFACE WITH CPU/FPGA RESET OUTPUT



7.2 Configuration Mode Pins (Strapping Options)

The configuration mode pins of the KSZ8061MNX (**CONFIG[2:0]**) control the default configuration of the 10/100 PHY. PHY Address, auto-negotiation, NAND tree, and Quiet-Wire functionality also can be configured through other strap pins. The values of these strap pins are latched upon power-up and reset. In some systems, the MAC receive input pins may drive high during power-up or reset and consequently cause the PHY strap-in pins on the MII signals to be latched high. In this case, it is recommended to add 1 k Ω pull-downs on these PHY strap-in pins to ensure that the PHY does not strap in to Quiet-Wire mode or is not configured with an incorrect PHY address. Refer to the *KSZ8061MNX Data Sheet* for complete details for the operation of these pins.

7.3 LED Pins

The KSZ8061MNX provides one LED signal. These indicators display speed, link, and activity information about the current state of the PHY. The LED pins drive low to light up the LED indicators, which should have their anode ends tied through a series resistors (typically 220 Ω -470 Ω) to **VDDIO** and their cathode ends tied to the KSZ8061MNX LED pin. Refer to the *KSZ8061MNX Data Sheet* for further details on how to connect each pin for correct operation.

Note 1: If using RJ45 jacks with integrated LEDs and 1.8V VDDIO, a level shifting is required from LED 3.3V to 1.8V. In this case, a bipolar transistor or a level shifting device can be used.

8.0 MISCELLANEOUS

8.1 REXT Resistor

The **REXT** pin on the KSZ8061MNX must connect to ground through a 6.04 k Ω resistor with a tolerance of 1.0%. This is used to set up critical bias currents for the embedded 10/100 Ethernet physical device.

8.2 Other Considerations

- Incorporate a large SMD footprint (SMD_1210) to connect the chassis ground to the digital ground. This allows some flexibility at EMI testing for different grounding options. Leaving the footprint open allows the two grounds to remain separate. Shorting them together with a zero ohm resistor connects them. For best performance, short them together with a cap or a ferrite bead.
- Be sure to incorporate enough bulk capacitors (4.7-22 μ F) for each power plane.

9.0 HARDWARE CHECKLIST SUMMARY

TABLE 9-1: HARDWARE DESIGN CHECKLIST

Section	Check	Explanation	✓	Notes
Section 2.0, "General Considerations"	Section 2.1, "Pin Check"	Verify that the pins match the data sheet.		
	Section 2.2, "Ground"	Verify that the grounds are tied to the ground paddle.		
Section 3.0, "Power"	Section 3.0, "Power"	• VDDIO requires a 10 μF capacitor and a 0.1 μF capacitor. • AVDDH requires a 10 μF capacitor and a 0.1 μF capacitor. • AVDDL requires a 10 μF capacitor and a 0.1 μF capacitor. • VDDL requires a 10 μF capacitor and a 0.1 μF capacitor.		
Section 4.0, "Ethernet Signals"	Section 4.1, "PHY Interface"	Verify that the TX and RX pins do not contain any termination resistors.		
	Section 4.2, "Magnetics Connection"	Verify that the center taps are connected to the GND using separate 0.1 μ F capacitors on the KSZ8061MNX device side, and are terminated with 75 Ω resistors through a 1000 pF, 2 kV capacitor to chassis ground on the RJ45 line side.		
	Section 4.3, "RJ45 Connection"	Verify pins 4/5 and 7/8 of the RJ45 connect to CAT-5 cable and are terminated to chassis ground through a 1000 pF, 2 kV capacitor.		
Section 5.0, "Clock Circuit"	Section 5.1, "Crystal and External Oscillator/ Clock Connections for MII Mode"	Verify usage of 25 MHz $\pm$ 50 ppm crystal/oscillator.		
Section 6.0, "Digital Interfaces"	Section 6.1, "MII Interface", Section 6.2, "Required External Pull-ups"	Confirm proper MII signals between MAC and PHY interface with correct termination resistors (33 Ω) and external pull-up for MDIO signal.		
Section 7.0, "Startup"	Section 7.1, "Reset Circuit"	Confirm proper reset circuit design: standalone reset or external CPU/FPGA reset.		
	Section 7.2, "Configuration Mode Pins (Strapping Options)"	In systems where the MAC receive input pins are driven high after reset, it is recommended to add 1 k Ω pull-downs on the PHY strap pins.		
	Section 7.3, "LED Pins"	If used, confirm proper connections, taking into consideration shared functionality on select LED pins.		
Section 8.0, "Miscellaneous"	Section 8.1, "REXT Resistor"	Confirm proper REXT resistor (6.04 k Ω , 1.0%).		
	Section 8.2, "Other Considerations"	Incorporate a large SMD footprint (SMD_1210) to connect the chassis ground to the chip ground instead of the digital ground. Incorporate sufficient power plane bulk capacitors (4.7-22 μ F).		

APPENDIX A: REVISION HISTORY

TABLE A-1: REVISION HISTORY

Revision Level & Date	Section/Figure/Entry	Correction
DS00004565A (05-18-22)	Initial release	

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